CHIMEI
a step up

奇美實業股份有限公司
717010 台南市仁德區中正路一段 398 號
+886-6-266-3000
www.chimeicorp.com

CHIMEI CORPORATION
No. 398 , Sec. 1 , Zhongzheng
Rd., Rende Dist., Tainan City
717010 , Taiwan

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Bulletin

We hereby certify that the resins below produced by CHIMEI CORPORATION

POLYLAC® ABS PA-763, PA-763A, PA-764, PA-764B, PA-764G

conforms to the requirement that no chemicals as following are intentionally added.

1. PBDEs (Polybrominated Diphenyl Ethers)
2. PBBs (Polybrominated Biphenyls)
3. Ozone Depleting Chemicals (CFCs & HCFCs)
4. Chlorinated Paraffin (C10-C13)
5. Polyvinyl Chloride (PVC)
6. Mercury (Hg) and its compounds
7. Lead (Pb) and its compounds
8. Cadmium (Cd) and its compounds
9. Chromium (Cr) and its compounds
10. Arsenic (As) and its compounds
11. Selenium (Se) and its compounds
12. Barium (Ba) and its compounds
13. Beryllium (Be) and its compounds
14. Bismuth (Bi) and its compounds
15. Organic tin compounds (TBT, TPT, DOT, DBT)
16. Polychlorinated Biphenyls (PCBs) and Terphenyls (PCTs) and Naphtalenes (PCNs)
17. Poly naphthalenes
18. Azo colorants (according to REACH-ANNEX-XVII-APPENDIX 8)
19. Asbestos
20. Phthalates
21. APEO: Including Alkylphenol(AP), Octylphenol(OP), Nonylphenol(NP), Octylphenol ethoxylates(OPE), Nonylphenol ethoxylates(NPE)
22. 2-(2'-Hydroxy-3',5'-di-tert-butylphenyl)benzotriazole
23. PFOA, PFOS, PFAS
24. Bisphenol A
35. Perchlorate
36. Hexachlorobenzene
37. Mirex
38. Specified amine compounds
39. Benzene
40. Benzenamine, *N*-phenyl-, Reaction Products with Styrene and 2,4,4-Trimethylpentene (BNST)
41. Polyamide
42. PVDC (polyvinylidene chloride)
43. ESBO (Expoxidized soybean oil)
44. Formamide
45. Hexabromocyclododecane (HBCDD)
46. Red phosphorus
47. Aniline · formaldehyde polycondensate
48. Fluorescent powder
49. 4,4’-Sulfonyldiphenol (BPS)
50. Tris (2-chloro-1-methylethyl) phosphate (TCPP)
51. Tris (1,3-Dichloro-2-propyl) phosphate (TDCPP)
52. Tris (2,3-dibromopropyl) phosphate
53. Tris (aziridinyl) phosphinoxide
54. Tri-o-cresyl phosphate
55. Tris (2-chloroethyl) phosphate (TCEP)
56. Perfluorohexane-1-sulphonic acid and its salts (PFHxS)
57. Diisononyl phthalate (DINP)
58. Di-isodecyl phthalate (DIDP)
59. Di-n-octyl phthalate (DnOP)
60. Diethyl phthalate (DEP)
61. Dimethyl phthalate (DMP)
62. Cobalt
63. Mica

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25. Formaldehyde
26. Dimethylfumarate (DMF)
27. Triclosan
28. Nickel
29. PAHs (Polycyclic Aromatic Hydrocarbons)
30. REACH- Candidate List of 235 SVHCs(2023/06/14)
31. Radioactive Substances
32. Natural Latex
33. Dioxins and furans
34. Primary aromatic amines (PAA)
64. Graphite
65. Bis (2-ethylhexyl) phthalate (DEHP)
66. Butyl benzyl phthalate (BBP)
67. Dibutyl phthalate (DBP)
68. Diisobutyl phthalate (DIBP)
69. PIP (3:1) (phenol, isopropylated phosphate 3:1)
70. DecaBDE (decabromodiphenyl ether)
71. 2,4,6-TTBP (2,4,6-Tris(tert-butyl)phenol)
72. HCBD (hexachlorobutadiene)
73. PCTP (pentachlorothiophenol)

With regard to composition of above grades of products, the aforesaid products comply with the Directives of RoHS 2011/65/EU and its amendment (EU) 2015/863

Sincerely Yours,

Jones. Kuo

Jones Kuo

Vice President of Research and Development Head Division

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